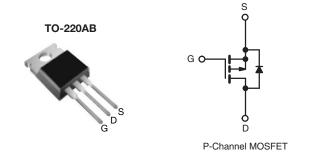


COMPLIANT

## Power MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	- 60			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = - 10 V	0.14		
Q <sub>g</sub> (Max.) (nC)	34			
Q <sub>gs</sub> (nC)	9.9			
Q <sub>gd</sub> (nC)	16			
Configuration	Single			



### **FEATURES**

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- P-Channel
- 175 °C Operating Temperature
- Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC

#### **DESCRIPTION**

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9Z34PbF
	SiHF9Z34-E3
SnPb	IRF9Z34
	SiHF9Z34

PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	- 60	.,,	
Gate-Source Voltage	V <sub>GS</sub>	± 20	- V		
Continuous Drain Current	$V_{GS}$ at - 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$	I-	- 18	А	
	$T_C = 100 ^{\circ}$ C	I <sub>D</sub>	- 13		
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	- 72			
Linear Derating Factor			0.59	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	370	mJ		
Repetitive Avalanche Current <sup>a</sup>	I <sub>AR</sub>	- 18	Α		
Repetitive Avalanche Energy <sup>a</sup>	E <sub>AR</sub>	8.8	mJ		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	88	W	
Peak Diode Recovery dV/dt <sup>c</sup>		dV/dt	- 4.5	V/ns	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>		
Mounting Torque	C 00 M0		10	lbf ⋅ in	
	6-32 or M3 screw		1.1	N · m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD} = -25$  V, starting  $T_J = 25$  °C, L = 1.3 mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = -18$  A (see fig. 12). c.  $I_{SD} \le -18$  A,  $dI/dt \le 170$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.7	

PARAMETER	SYMBOL	TEST (	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 60	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = - 1 mA		-	- 0.060	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{c}$	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		-	- 4.0	٧
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>G</sub>	V <sub>GS</sub> = ± 20 V		-	± 100	nA
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 0	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V		-	- 100	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 48 V, V	$t_{\rm GS} = 0 \text{ V}, T_{\rm J} = 150 ^{\circ}\text{C}$	-	-	- 500	μΑ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 11 A <sup>b</sup>	-	-	0.14	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = - 2	V <sub>DS</sub> = - 25 V, I <sub>D</sub> = - 11 A <sup>b</sup>		-	1	S
Dynamic							
Input Capacitance	$C_{iss}$	V <sub>GS</sub> = 0 V,		-	1100	ı	pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub>	$V_{DS} = -25 \text{ V},$		620	-	
Reverse Transfer Capacitance	$C_{rss}$	f = 1.0 MHz, see fig. 5		-	100	-	
Total Gate Charge	$Q_g$	V <sub>GS</sub> = - 10 V	$I_D = -18 \text{ A},$ $V_{DS} = -48 \text{ V},$ see fig. 6 and 13 <sup>b</sup>	-	-	34	nC
Gate-Source Charge	Q <sub>gs</sub>			-	-	9.9	
Gate-Drain Charge	$Q_{gd}$			-	-	16	
Turn-On Delay Time	t <sub>d(on)</sub>			-	18	-	
Rise Time	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, I_{D} = -18 \text{ A},$ $R_{g} = 12 \Omega, R_{D} = 1.5 \Omega, \text{ see fig. } 10^{\text{b}}$		-	120	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			-	20	-	
Fall Time	t <sub>f</sub>			-	58	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal Source Inductance	L <sub>S</sub>			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	- 18	A
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	_	- 72	A
Body Diode Voltage	$V_{SD}$	T <sub>J</sub> = 25 °C, I <sub>S</sub> = - 18 A, V <sub>GS</sub> = 0 V <sup>b</sup>		-	-	- 6.3	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	$T_{\rm J} = 25~{\rm ^{\circ}C},~I_{\rm F} = -18~{\rm A},~{\rm dl/dt} = 100~{\rm A/\mu s^{b}}$		-	100	200	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	0.28	0.52	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and L <sub>D</sub> )				L <sub>D</sub> )	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %.



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

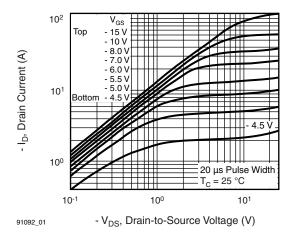


Fig. 1 - Typical Output Characteristics,  $T_C = 25$  °C

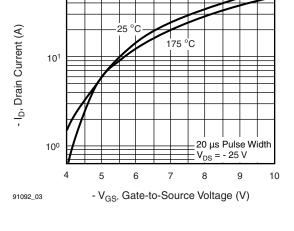


Fig. 3 - Typical Transfer Characteristics

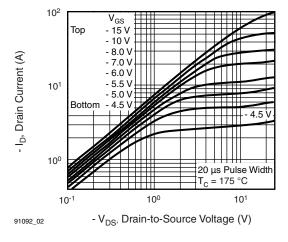


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 175 °C

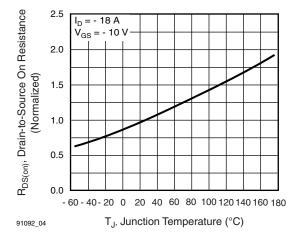


Fig. 4 - Normalized On-Resistance vs. Temperature



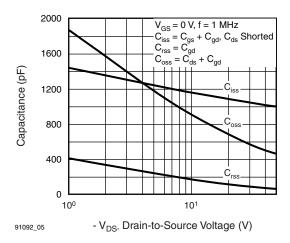


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

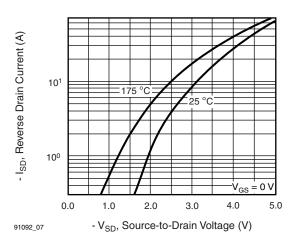


Fig. 7 - Typical Source-Drain Diode Forward Voltage

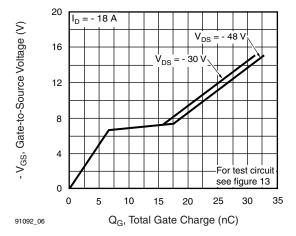


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

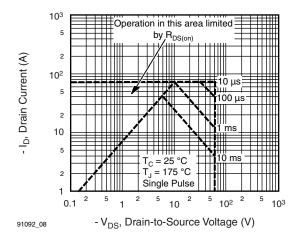


Fig. 8 - Maximum Safe Operating Area





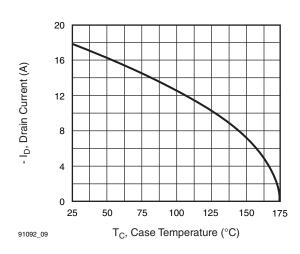


Fig. 9 - Maximum Drain Current vs. Case Temperature

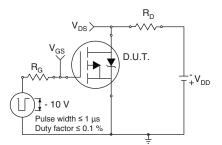


Fig. 10a - Switching Time Test Circuit

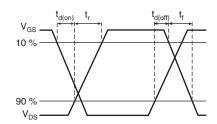


Fig. 10b - Switching Time Waveforms

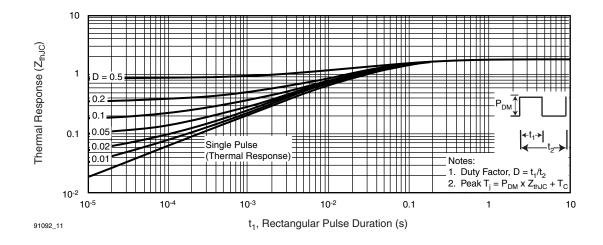


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



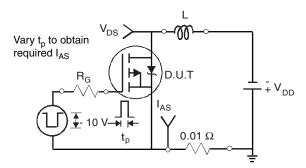


Fig. 12a - Unclamped Inductive Test Circuit

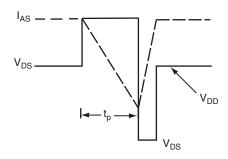


Fig. 12b - Unclamped Inductive Waveforms

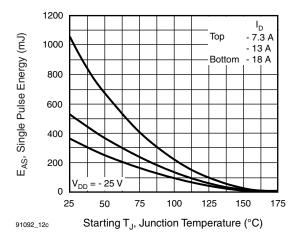


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

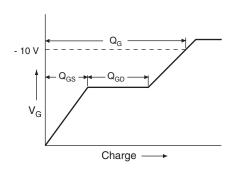


Fig. 13a - Basic Gate Charge Waveform

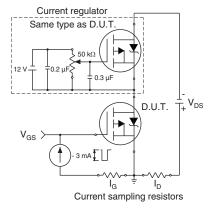
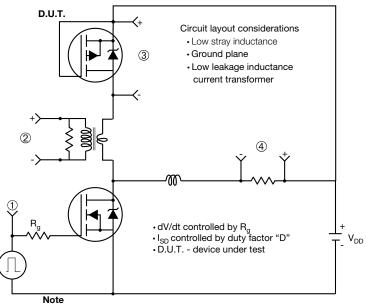


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



· Compliment N-Channel of D.U.T. for driver

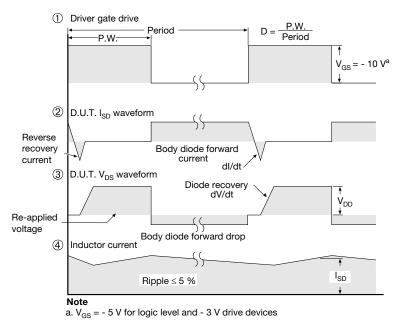


Fig. 14 - For P-Channel

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